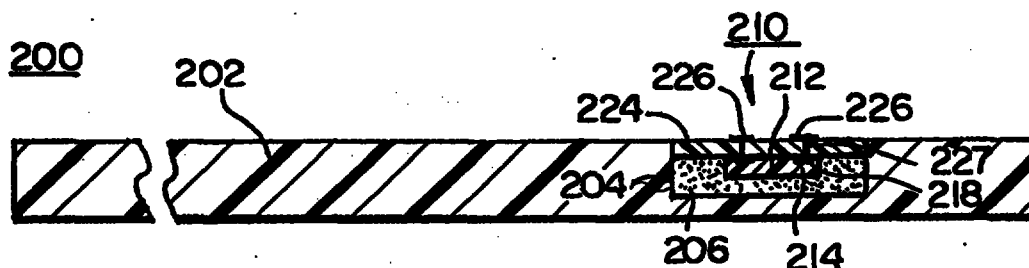


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(54) Title: ARTICLE HAVING AN EMBEDDED ELECTRONIC DEVICE, AND METHOD OF MAKING SAME



(57) Abstract

A card has an electronic device, such as an integrated circuit, or a conductive network (Fig. 3). The card, sometimes is referred to as a "smart card", has the electronic device (212) mounted to its surface, generally by electrical connections formed of solder, electrically conductive adhesive, or flexible electrically conductive adhesive (206). The card substrate is covered by a layer of melt-flowable adhesive of thickness sufficient to cover the electronic device (212) mounted thereon. The card substrate is attached to a card blank (202) to which it is bonded by melt flowing the melt-flowable adhesive. In one embodiment, the card blank has a cavity (204) into which the electronic device (212) and card substrate (224) are placed. In another embodiment, the card substrate (402) is of the same size and shape as is the card blank (420) and the space therebetween is filled with melt flowable adhesive (424) to bond them together and embed the electronic device (410) therebetween. Further, the card substrate may have a pattern of conductive adhesive deposited thereon, such as to form a loop antenna (404), which also serves to form electrical connections to the electronic device (Fig. 13).